*THE COMMISSIONER OF PATENTS AND TRADEMARKS Washington, D.C. 20231

Docket No. MEG01-013

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10/054001 10/054001 01/19/02

Washington, D.C. 20231

Sir:

Pransmitted herewith for filing is the Patent Application of:

Inventor: MOU SHUNG LIN, JIN-YUAN LEE, CHING-CHENG HUANG

THIN FILM SEMICONDUCTOR PACKAGE AND METHOD OF FABRICATION

Enclosed are:

x 22 sheets of drawing(s) - formal.

x An assignment of the invention to MEGIC Corp.

An associate power of attorney X Applicant claims small entity status

x Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

| | | (Col. 1) | (Col. 2) | | SMALL ENTITY |
|---------|--------------|-----------------|-----------|----------|--------------|
| | FOR: | NO. FILED | NO. EXTRA | RATE | FEE |
| | BASIC FEE | >< | >< | | \$ 740. |
| | TOTAL CLAIMS | 58 - 20= | 38 | x 9, = | \$ 342. |
| | INDEP CLAIMS | 9 -3= | 66 | x 42 = | \$ 252. |
| ja L | MULTIPLE | | | | |
| | | | S | UB TOTAL | \$ 594. |
| J. 40° | | SSIGNMENT | \$40. | | |
| | | | 'OTAL | s (e34. | |

Please charge my Deposit Account No. 19-0033 in the amount of \$ 634 . A duplicate copy of this sheet is enclosed.

x

NONPUBLICATION REQUEST UNDER 35 U.S.C. 122(b)(2)(B)(i)

| First N | lamed Inventor | Mou-Shinna Lin |
|---------|----------------|---|
| Title | And Metho | Mou-Shiung Lin semiconductor fackage d Of Fabrication |
| | ocket Number | MEGNI-013 |

I hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.

I hereby request that the attached application not be published under 35 U.S.C. 122(b).

1/19/02 Date

Signature

Stephen B. Ackerman Reg. #37,76,
Typed or printed name

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant must notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).